

Heat Sinking and Thermal Design

Figures 15, 16, 17 show an example of the recommended assembly for the HiperPFS-3. In this assembly, no insulation pad is required and HiperPFS-3 can be directly connected to the heat sink by mechanical clip or adhesive thermal compound.

The HiperPFS-3 back metal is electrically connected to the heat sink and the heat sink is required to be connected to the HiperPFS-3 source terminal in order to reduce EMI.

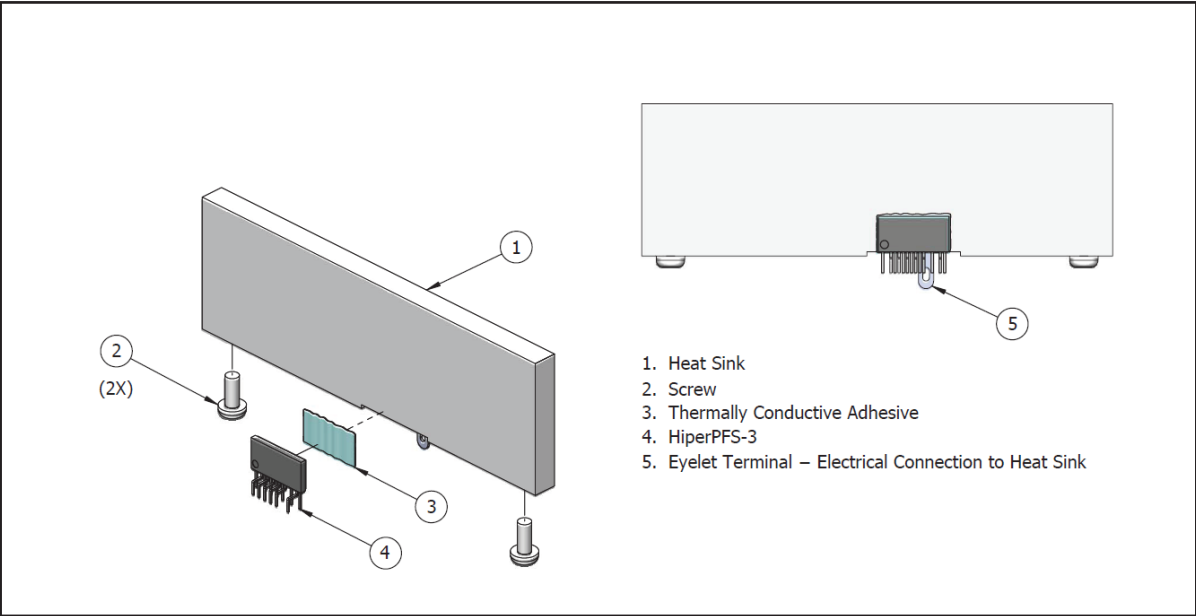


Figure 15. Heat Sink Assembly – using Thermally Conductive Adhesive.

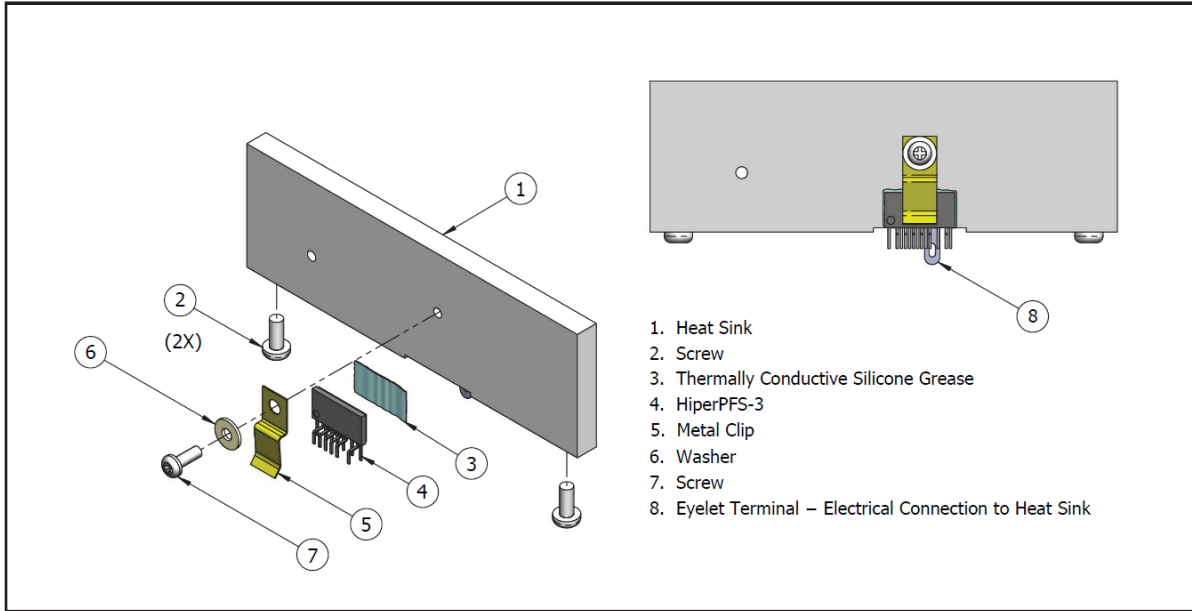


Figure 16. Heat Sink Assembly – with Metal Clip.

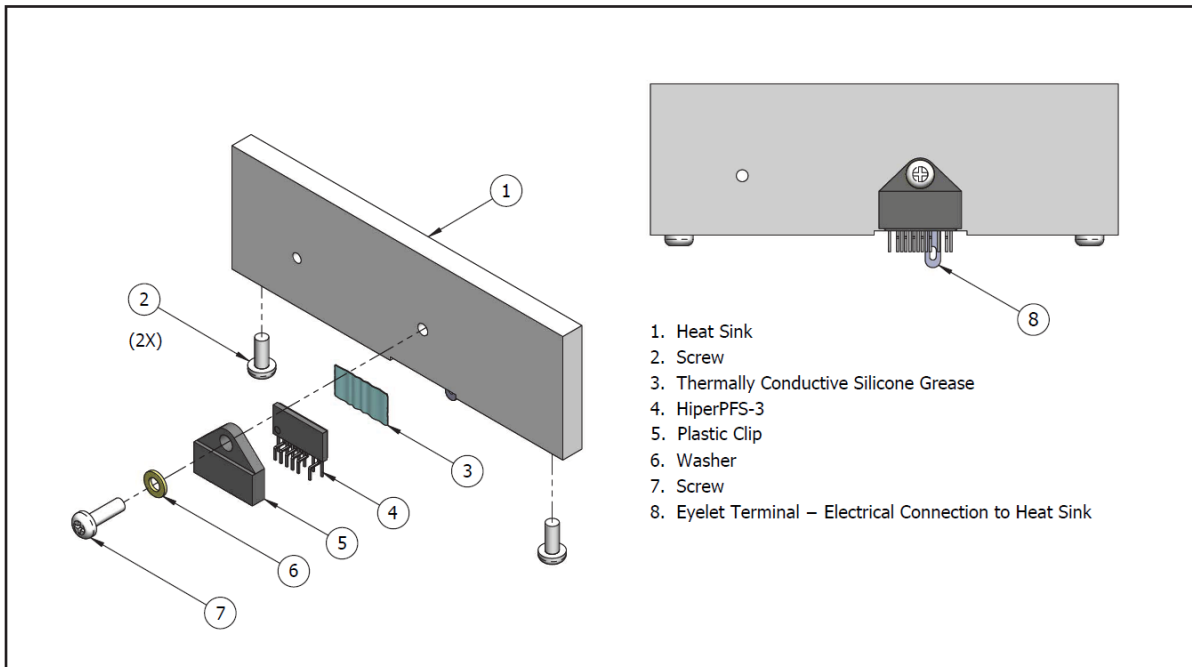


Figure 17. Heat Sink Assembly – with Plastic Clip.